PEELABLE CIRCUIT BOARD FOIL

Abstract of the Disclosure

In one embodiment, a peelable circuit board foil (**200**) has a metal support layer (**205**) and a conductive metal foil layer (**210**) bonded by an inorganic release material (**215**). The conductive metal foil layer has a surface (**212**) that is coated with a high temperature anti-oxidant barrier (**220**) and has a roughness less than 0.05 microns RMS. In a second embodiment, the peelable printed circuit foil (**200**) has a crystallized dielectric oxide layer (405) disposed on the metal foil layer and an electrode layer (**415**) disposed on the crystallized dielectric oxide layer, forming a dielectric peelable circuit board foil (**400**) that may be adhered to a layer of a flexible or rigid circuit board, after which the metal support layer can be peeled away, leaving a capacitive structure including the metal foil layer, the crystallized dielectric oxide layer, and the electrode layer. The capacitive structure can be used to form a plurality of capacitors in the printed circuit board.